



# CELANEX® 2000-K

unfilled, very low viscosity PBT polymer grade

Celanex 2000-K is a general purpose, unreinforced polybutylene terephthalate with a good balance of mechanical properties and processability. Celanex 2000-K is a high flow material suitable for homogenous and bicomponent spunbond fiber applications as well as injection molding.

#### **Product information**

Product information		
Part Marking Code	> PBT <	ISO 11469
Rheological properties		
Melt volume-flow rate	65 cm <sup>3</sup> /10min	ISO 1133
Melt mass-flow rate	70 g/10min	ISO 1133
Temperature	250 °C	
Load	2.16 kg	
Melt mass-flow rate, Temperature	250 °C	
Melt mass-flow rate, Load	2.16 kg	
Typical mechanical properties		
Tensile Modulus	2700 MPa	ISO 527-1/-2
Yield stress, 50mm/min	60 MPa	ISO 527-1/-2
Yield strain, 50mm/min	4 %	ISO 527-1/-2
Nominal strain at break	30 %	ISO 527-1/-2
Strain at break, 50mm/min	30 %	ISO 527-1/-2
Flexural Modulus	2600 MPa	ISO 178
Flexural Strength	85 MPa	ISO 178
Charpy impact strength, 23°C	100 kJ/m <sup>2</sup>	ISO 179/1eU
Charpy impact strength, -30°C	90 kJ/m²	ISO 179/1eU
Charpy notched impact strength, 23°C	4 kJ/m²	ISO 179/1eA
Charpy notched impact strength, -30°C	3.5 kJ/m <sup>2</sup>	ISO 179/1eA
Izod notched impact strength, 23°C	3.2 kJ/m <sup>2</sup>	ISO 180/1A
Hardness, Rockwell, M-scale	75	ISO 2039-2
Thermal properties		
Melting temperature, 10 °C/min	225 °C	ISO 11357-1/-3
Glass transition temperature, 10°C/min	60 °C	ISO 11357-1/-3
Temp. of deflection under load, 1.8 MPa	55 °C	ISO 75-1/-2
Temp. of deflection under load, 0.45 MPa	155 °C	ISO 75-1/-2
Vicat softening temperature, 50°C/h, 50N	190 °C	ISO 306
Coeff. of linear therm. expansion, parallel	110 E-6/K	ISO 11359-1/-2
Coeff. of linear therm. expansion, normal	100 E-6/K	ISO 11359-1/-2

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#### Flammability

Burning Behav. at thickness h	HB	class	UL 94
Thickness tested	0.71	mm	UL 94
Oxygen index	22	%	ISO 4589-1/-2

#### **Electrical properties**

Relative permittivity, 100Hz	4	IEC 62631-2-1
Relative permittivity, 1MHz	3.5	IEC 62631-2-1
Dissipation factor, 100Hz	15 E-4	IEC 62631-2-1
Dissipation factor, 1MHz	200 E-4	IEC 62631-2-1
Volume resistivity	>1E13 Ohm.m	IEC 62631-3-1
Surface resistivity	>1E15 Ohm	IEC 62631-3-2
Electric strength	23 kV/mm	IEC 60243-1
Comparative tracking index	PLC 0 PLC	UL 746A

#### Other properties

Humidity absorption, 2mm	0.25 %	Sim. to ISO 62
Water absorption, 2mm	0.45 %	Sim. to ISO 62
Density	1310 kg/m <sup>3</sup>	ISO 1183

### Injection

Drying Temperature	120 - 130	°C
Drying Time, Dehumidified Dryer	4	h
Processing Moisture Content	0.02	%
Max. mould temperature	65 - 93	°C
Injection speed	medium-fast	

#### Additional information

Injection molding

Rear Temperature 450-470(230-240) deg F (deg C)
Center Temperature 460-480(235-250) deg F (deg C)
Front Temperature 470-500(240-260) deg F (deg C)
Nozzle Temperature 480-500(250-260) deg F (deg C)
Melt Temperature 460-500(235-260) deg F (deg C)
Mold Temperature 150-200(65-93) deg F (deg C)
Back Pressure 0-50 psi
Screw Speed Medium
Injection Speed Fast

Injection speed, injection pressure and holding pressure have to be optimized to the individual article geometry. To avoid material degradation during processing low back pressure and minimum screw speed have to be used. Overheating of the material has to be avoided, in particular for flame retardant grades. Up to 25% clean and dry regrind may be used.

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**Processing Texts** 

Pre-drying To avoid hydrolytic degradation during processing, CELANEX resins have to be

dried to a moisture level equal to or less than 0.02%. Drying should be done in a dehumidifying hopper dryer capable of dewpoints <-40°F (-40°C) at 250°F

(121°C) for 4 hours.

Longer pre-drying times/storage For subsequent storage of the material in the dryer until processed (<= 60 h) it is

necessary to lower the temperature to 100° C.

Injection molding Rear Temperature 450-470(230-240) deg F (deg C)

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Injection molding Preprocessing To avoid hydrolytic degradation during processing, CELANEX resins have to be

dried to a moisture level equal to or less than 0.02%. Drying should be done in a dehumidifying hopper dryer capable of dewpoints <-30°F (-34°C) at 250°F

(121°C) for 4 hours.